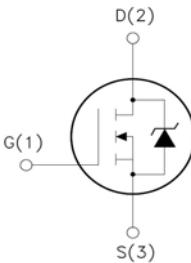


<b>85N06</b> 60V N-Channel MOSFET  <b>Features:</b> <ul style="list-style-type: none"> <li><input type="checkbox"/> Low Intrinsic Capacitances.</li> <li><input type="checkbox"/> Excellent Switching Characteristics.</li> <li><input type="checkbox"/> Extended Safe Operating Area.</li> <li><input type="checkbox"/> Unrivalled Gate Charge :Qg= 72nC (Typ.).</li> <li><input type="checkbox"/> BVDSS=60V,I D=85A</li> <li><input type="checkbox"/> RDS(on) : 8.5mΩ (Max) @VG=10V</li> <li><input type="checkbox"/> 100% Avalanche Tested</li> </ul>	 <b>TO-220F</b>   1.Gate (G) 2.Drain (D) 3.Source (S)
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**Absolute Maximum Ratings\* (Tc=25°C Unless otherwise noted)**

Symbol	PARAMETER	Value	Unit
$V_{DSS}$	Drain-Source Voltage	60	V
$I_D$	Drain Current	$T_c=25^\circ\text{C}$	85
		$T_c=100^\circ\text{C}$	65
$V_{GS(TH)}$	Gate Threshold Voltage	$\pm 25$	V
$E_{AS}$	Single Pulse Avalanche Energy (note1)	100	mJ
$I_{AR}$	Avalanche Current (note2)	85	A
$P_D$	Power Dissipation ( $T_c=25^\circ\text{C}$ )	65	W
$T_j$	Junction Temperature(MAX)	150	°C
$T_{stg}$	Storage Temperature	-55~+150	°C
$T_L$	Maximum lead temperature for soldering purpose, 1/8" from case for 5 seconds	300	°C

**Thermal Characteristics**

Symbol	PARAMETER	Typ.	MAX.	Unit
$R_{\theta JC}$	Thermal Resistance,Junction to Case	-	1.92	°C/W
$R_{\theta JA}$	Thermal Resistance,Junction to Ambient	-	62.5	°C/W

**Electrical Characteristics ( $T_c=25^\circ\text{C}$  unless otherwise noted)**

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>On/off states</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	60	-	-	V
Zero Gate Voltage Drain Current( $T_c=25^\circ\text{C}$ )	$I_{\text{DSS}}$	$V_{\text{DS}}=60\text{V}, V_{\text{GS}}=0\text{V}$	-	-	1	$\mu\text{A}$
Zero Gate Voltage Drain Current( $T_c=125^\circ\text{C}$ )	$I_{\text{DSS}}$	$V_{\text{DS}}=48\text{V}, V_{\text{GS}}=0\text{V}$	-	-	10	$\mu\text{A}$
Gate-Body Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}=\pm 30\text{V}, V_{\text{DS}}=0\text{V}$	-	-	$\pm 100$	nA
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	2	-	4	V
Drain-Source On-State Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=40\text{A}$	-	7.5	8.5	$\text{m}\Omega$
<b>Dynamic Characteristics</b>						
Forward Transconductance	$g_{\text{FS}}$	$V_{\text{DS}}=5\text{V}, I_{\text{D}}=40\text{A}$	-	105	-	S
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}}=35\text{V}, V_{\text{GS}}=0\text{V}, F=1.0\text{MHz}$	-	3091	-	PF
Output Capacitance	$C_{\text{oss}}$		-	292	-	PF
Reverse Transfer Capacitance	$C_{\text{rss}}$		-	219	-	PF
Total Gate Charge	$Q_g$	$V_{\text{DS}}=32\text{V}, I_{\text{D}}=40\text{A}, V_{\text{GS}}=10\text{V}$	-	72	-	nC
Gate-Source Charge	$Q_{\text{gs}}$		-	17	-	nC
Gate-Drain Charge	$Q_{\text{gd}}$		-	26	-	nC
<b>Switching times</b>						
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=32\text{V}, I_{\text{D}}=40\text{A}, R_{\text{L}}=15\Omega, V_{\text{GS}}=10\text{V}, R_{\text{G}}=2.7\Omega$	-	13	-	nS
Turn-on Rise Time	$t_r$		-	75	-	nS
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$		-	46	-	nS
Turn-Off Fall Time	$t_f$		-	73	-	nS
<b>Source- Drain Diode Characteristics</b>						
Source-drain current(Body Diode)	$I_{\text{SD}}$		-	-	85	A
Pulsed Source-drain current(Body Diode)	$I_{\text{SDM}}$		-	-	300	A
Forward on voltage <sup>(Note 1)</sup>	$V_{\text{SD}}$	$T_j=25^\circ\text{C}, I_{\text{SD}}=85\text{A}, V_{\text{GS}}=0\text{V}$	-	-	1.5	V
Reverse Recovery Time <sup>(Note 1)</sup>	$t_{\text{rr}}$	$T_j=25^\circ\text{C}, I_F=85\text{A}, \frac{dI}{dt}=100\text{A}/\mu\text{s}$	-	36	-	nS
Reverse Recovery Charge <sup>(Note 1)</sup>	$Q_{\text{rr}}$		-	43	-	nC
Forward Turn-on Time	$t_{\text{on}}$	Intrinsic turn-on time is negligible(turn-on is dominated by $L_s+L_d$ )				

 Notes 1.Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 1.5\%$ ,  $R_G=25\Omega$ , Starting  $T_j=25^\circ\text{C}$

### Typical Electrical and Thermal Characteristics (curves)

Fig 1: Output Characteristics

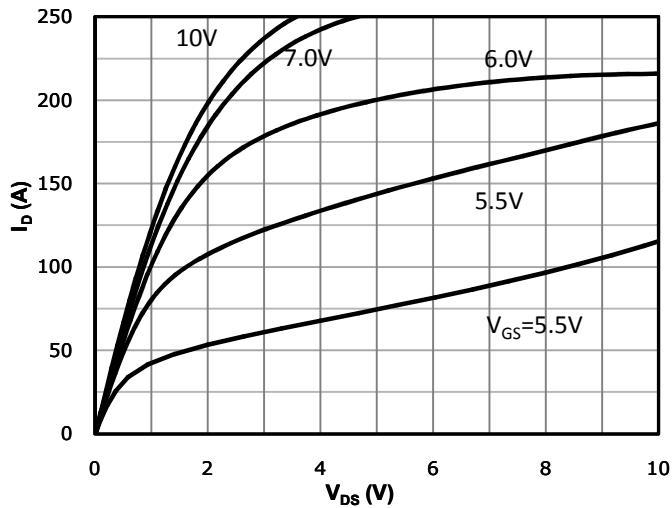


Fig 2: Transfer Characteristics

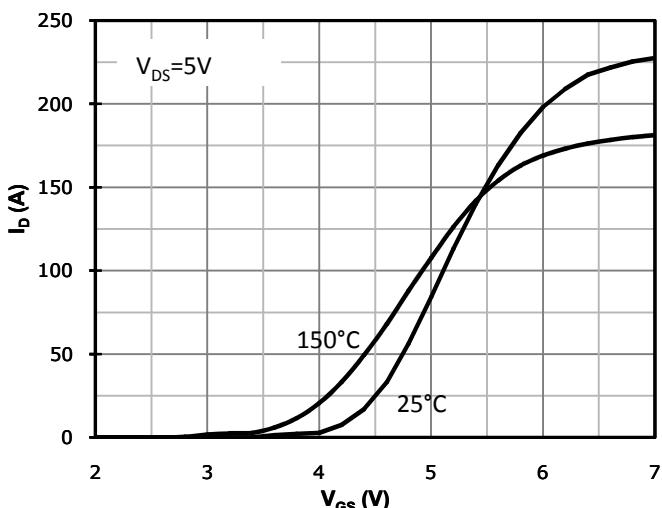


Fig 3:  $R_{DS(on)}$  vs Drain Current and Gate Voltage

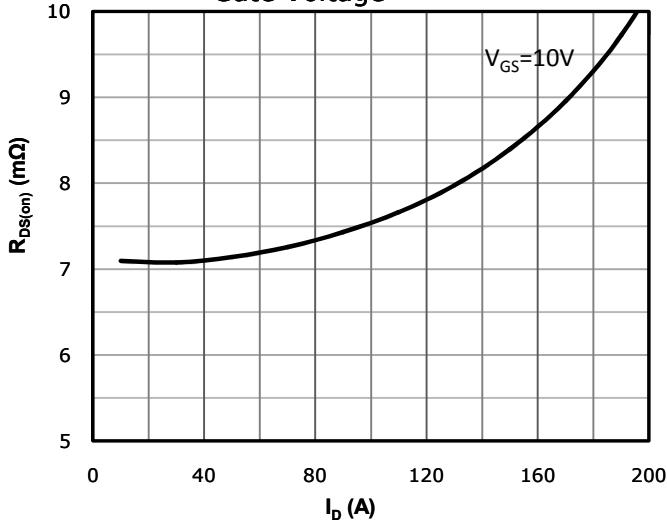


Fig 4:  $R_{DS(on)}$  vs Gate Voltage

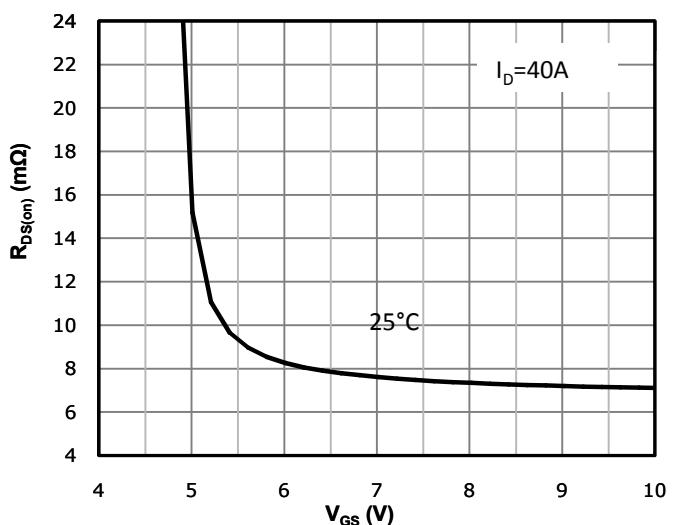


Fig 5:  $R_{DS(on)}$  vs. Temperature

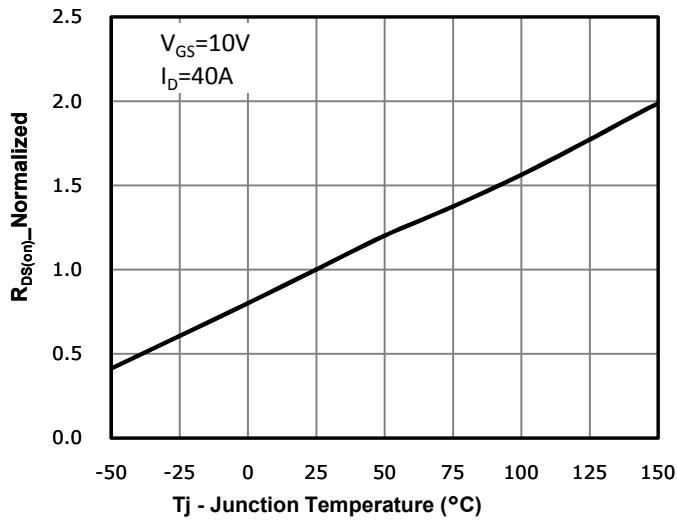
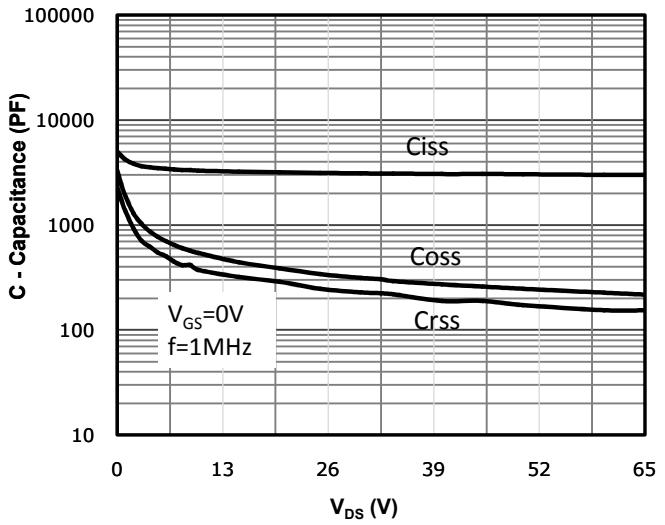


Fig 6: Capacitance Characteristics



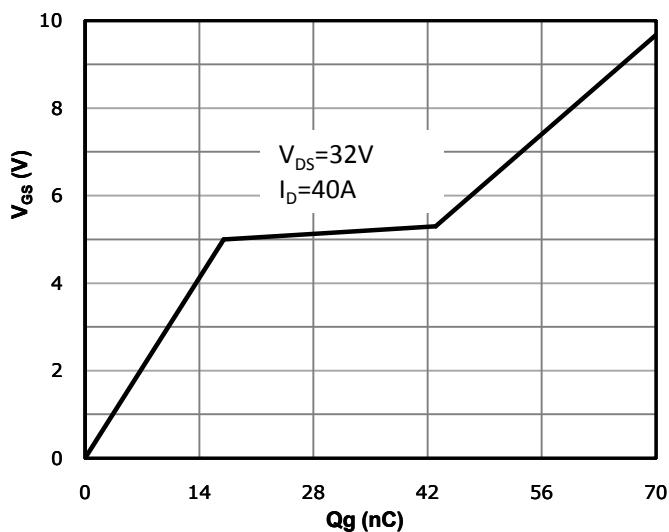
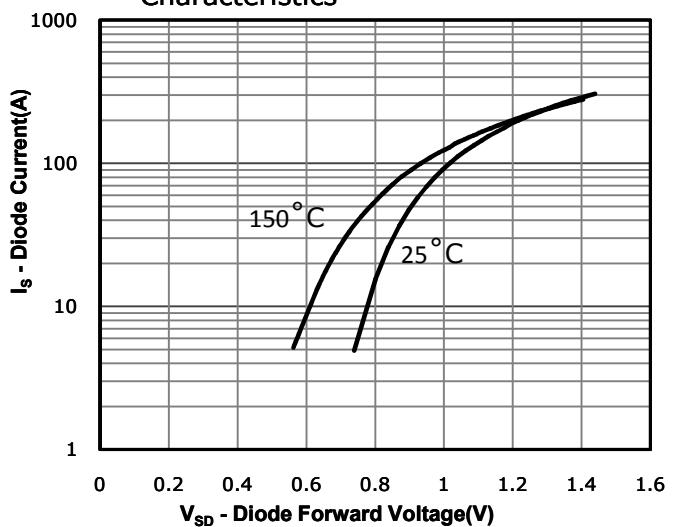
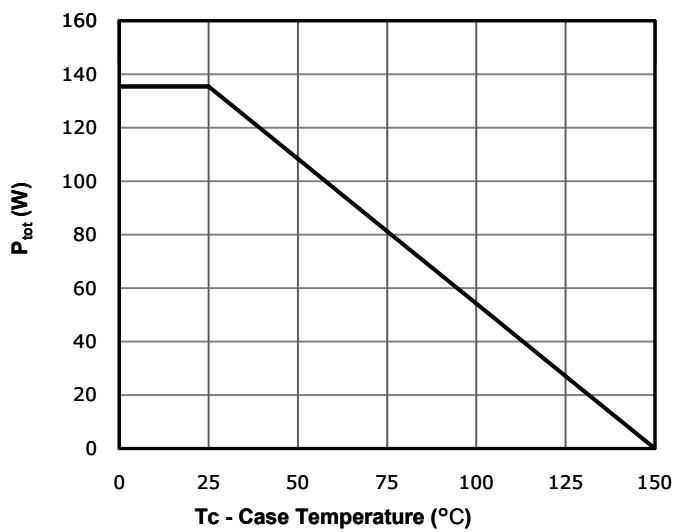
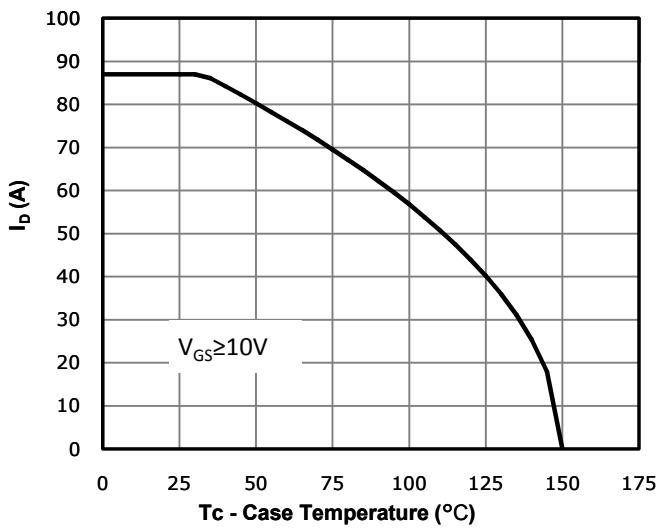
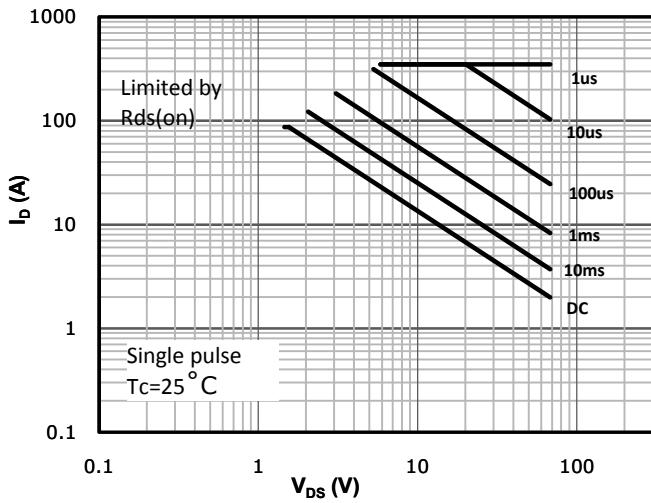
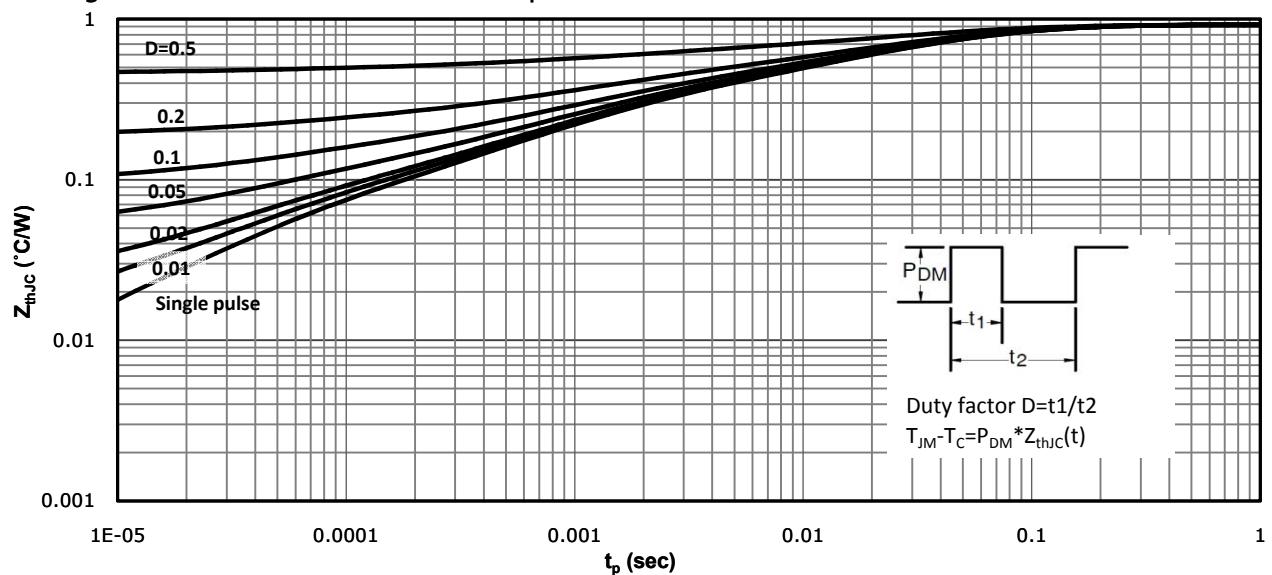
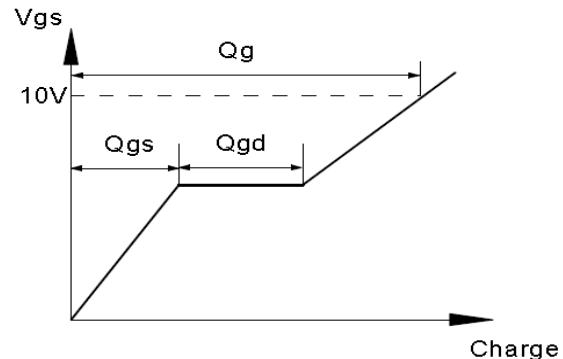
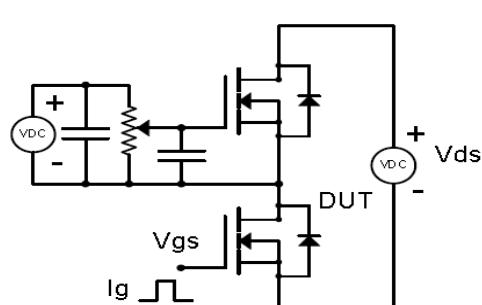
**Fig 7: Gate Charge Characteristics**

**Fig 8: Body-diode Forward Characteristics**

**Fig 9: Power Dissipation**

**Fig 10: Drain Current Derating**

**Fig 11: Safe Operating Area**


Fig 12: Max. Transient Thermal Impedance

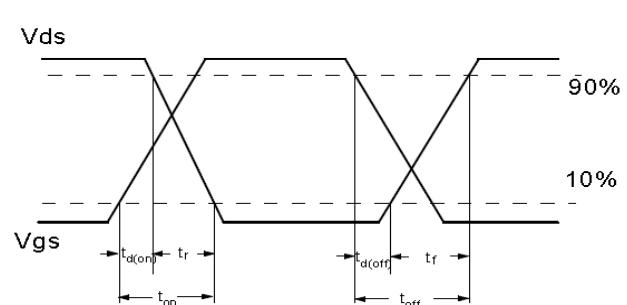
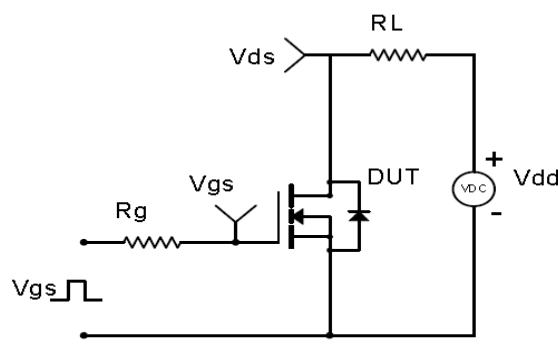


## Test Circuit & Waveform

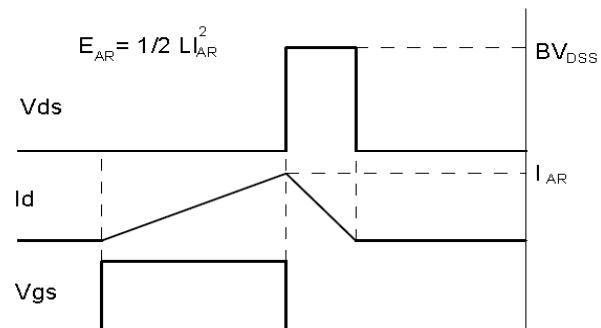
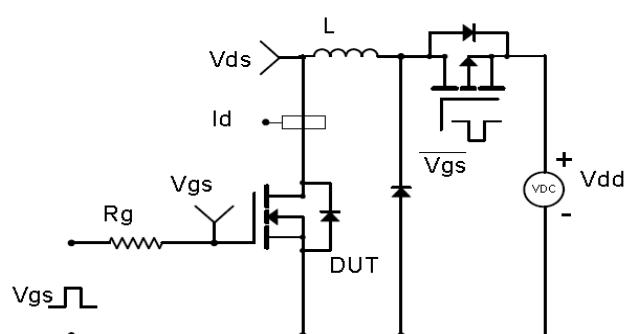
Gate Charge Test Circuit &amp; Waveform



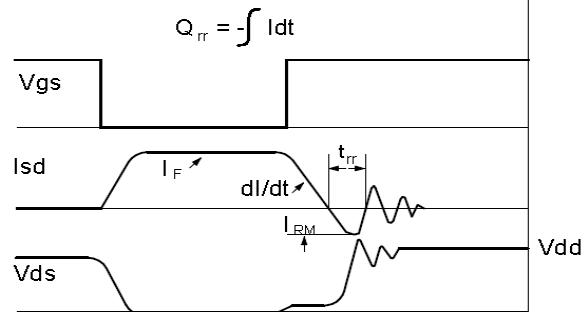
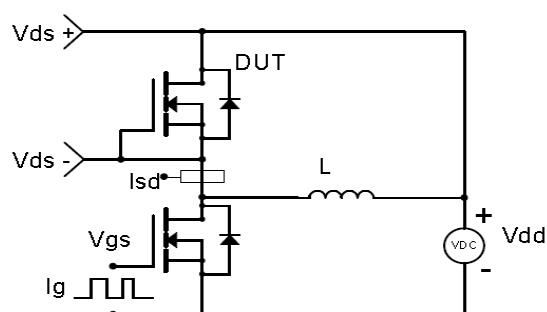
Resistive Switching Test Circuit &amp; Waveforms



Unclamped Inductive Switching (UIS) Test Circuit &amp; Waveforms



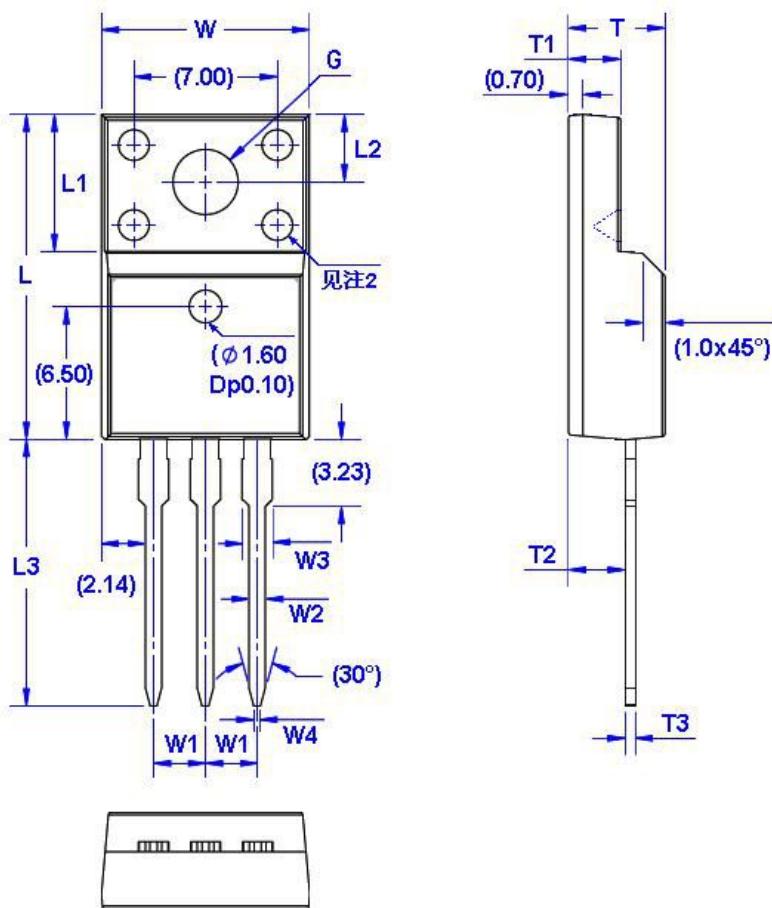
Diode Recovery Test Circuit &amp; Waveforms



## Package Dimension

TO-220F

Unit: mm



Symbol	Size		Symbol	Size		Symbol	Size		Symbol	Size	
	Min	Max		Min	Max		Min	Max		Min	Max
W	9.96	10.36	W4	0.25	0.45	L3	12.78	13.18	T3	0.45	0.60
W1	2.54 (TYP)		L	15.67	16.07	T	4.50	4.90	G(Φ)	3.08	3.28
W2	0.70	0.90	L1	6.48	6.88	T1	2.34	2.74			
W3	1.24	1.47	L2	3.20	3.40	T2	2.56	2.96			